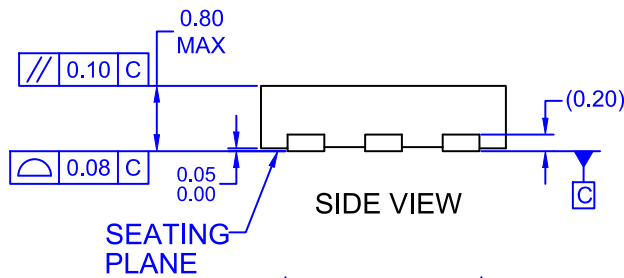
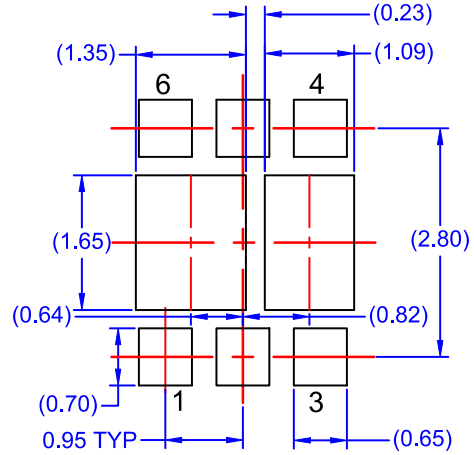
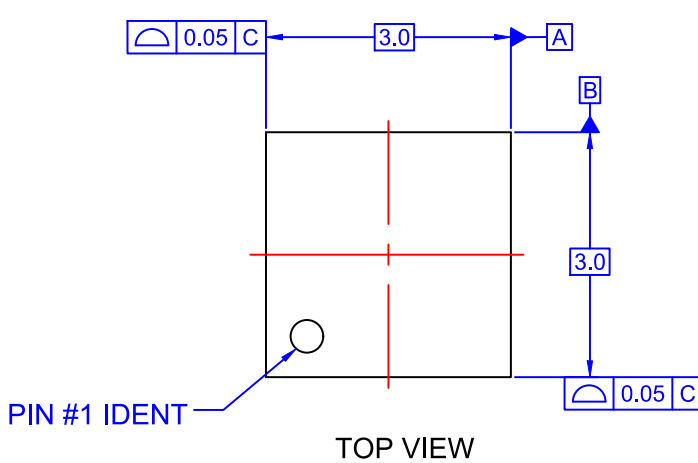


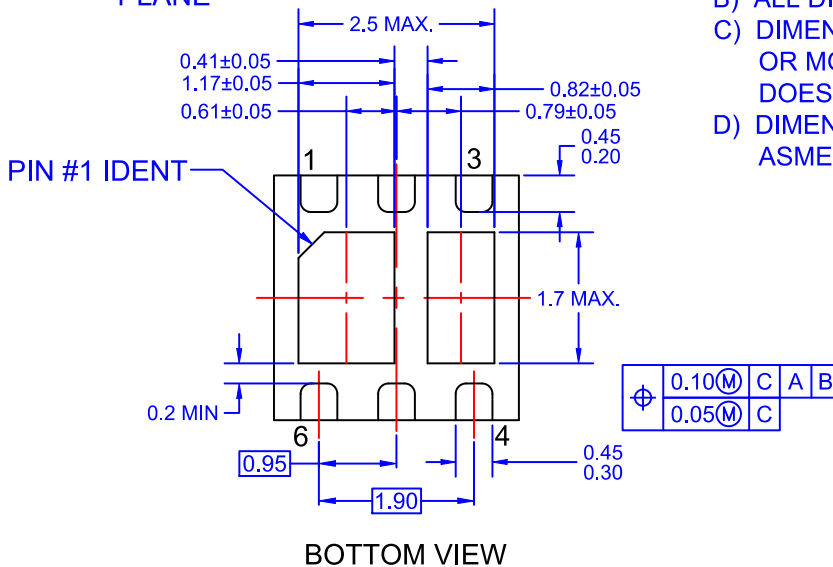
**WDFN6 3x3, 0.95P**  
CASE 511DT  
ISSUE O

DATE 31 DEC 2016



**RECOMMENDED LAND PATTERN**

- NOTES: UNLESS OTHERWISE SPECIFIED  
 A) CONFORMS TO JEDEC REGISTRATION, MO-229, VARIATION WEEA  
 B) ALL DIMENSIONS ARE IN MILLIMETERS.  
 C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.  
 D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.



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<b>DESCRIPTION:</b>	<b>WDFN6 3x3, 0.95P</b>	<b>PAGE 1 OF 1</b>

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